

Product Summary (@T_A = +25°C)

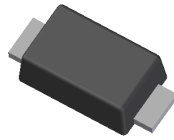
V _{RRM} (V)	I _O (A)	V _{F max} (V)	I _{R max} (μA)
40	3	0.53	30

Description

Packaged in the compact thermally efficient POWERDI-123 package, the SBRT3M40P1 provides very low reverse leakage and excellent V_F stability at high temperatures. It is ideally suited to use as a rectifier diode in MR16 bridge rectifier applications.

Applications

- Bridge Rectifier Diode



Top View



Device symbol

Features and Benefits

- Reduced ultra-low forward voltage drop (V_F); better efficiency and cooler operation.
- Reduced high temperature reverse leakage; Increased reliability against thermal runaway failure in high temperature operation.
- <1.1mm package profile – ideal for thin applications.
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**

Mechanical Data

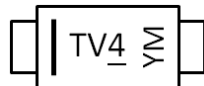
- Case: PowerDI123
- Case Material: Molded Plastic, “Green” Molding compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 Ⓔ
- Polarity: Cathode Band
- Weight: 0.01 grams (approximate)

Ordering Information (Note 4)

Part Number	Case	Packaging
SBRT3M40P1-7	PowerDI123	3000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated’s definitions of Halogen- and Antimony-free, “Green” and Lead-free.
 3. Halogen- and Antimony-free “Green” products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



TV4 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: A = 2013)
 M = Month (ex: 9 = September)

Date Code Key

Year	2013	2014	2015	2016	2017	2018	2019	2020
Code	A	B	C	D	E	F	G	H

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	40	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
Average Rectified Output Current	I _O	3	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	70	A

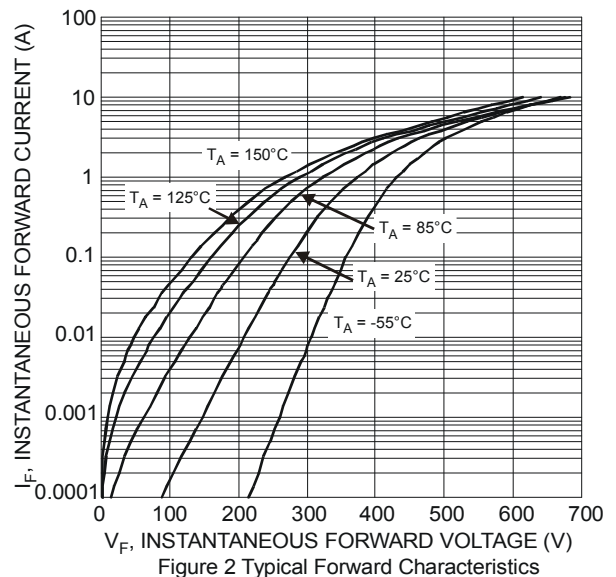
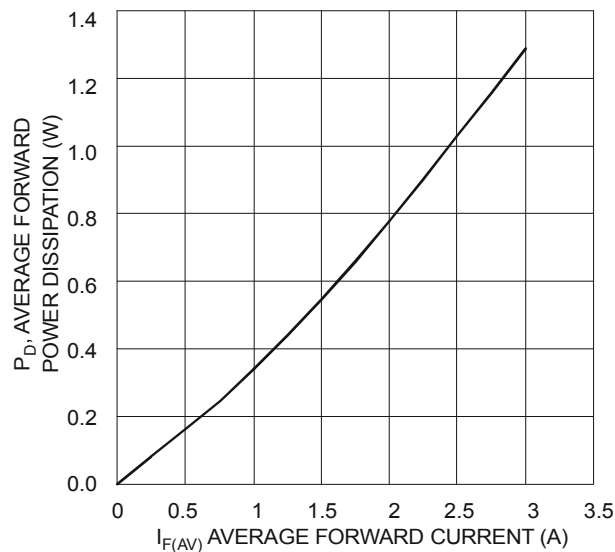
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	78	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R _{θJC}	16	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop (Note 6)	V _F	—	0.37	0.42	V	I _F = 1A, T _J = +25°C
		—	0.29	—		I _F = 1A, T _J = +125°C
		—	0.46	0.53		I _F = 3A, T _J = +25°C
		—	0.41	—		I _F = 3A, T _J = +125°C
Leakage Current (Note 6)	I _R	—	8	30	μA	V _R = 40V, T _J = +25°C
		—	2.2	15		mA

Notes: 5. Device mounted on 1 inch FR4.
6. Short duration pulse test used to minimize self-heating effect.



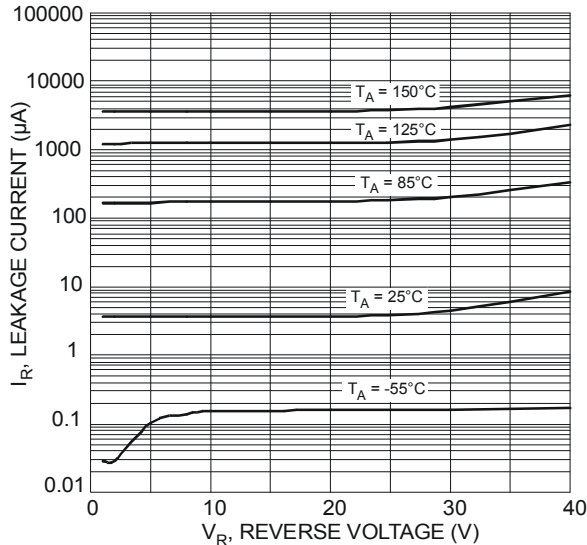


Figure 3 Typical Reverse Characteristics

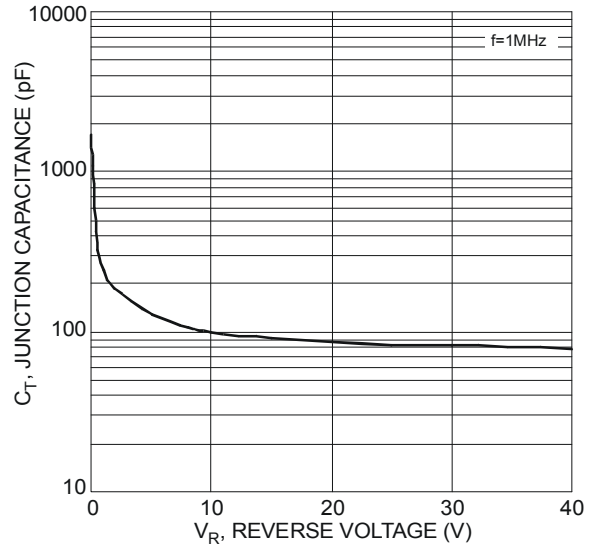


Figure 4 Typical Junction Capacitance

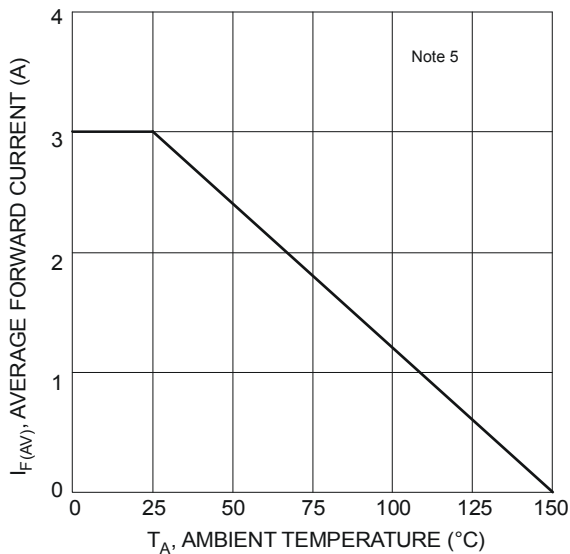


Figure 5 Forward Current Derating Curve

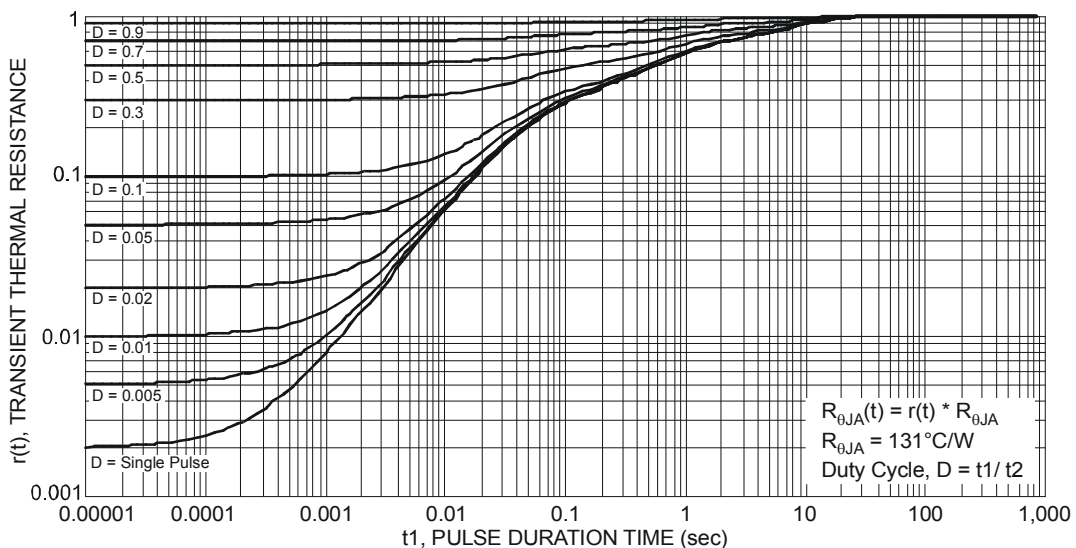
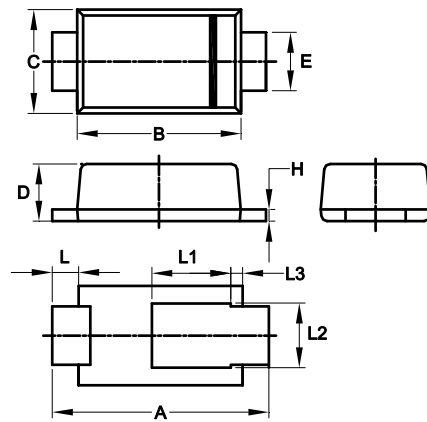


Figure 6 Transient Thermal Resistance

Package Outline Dimensions

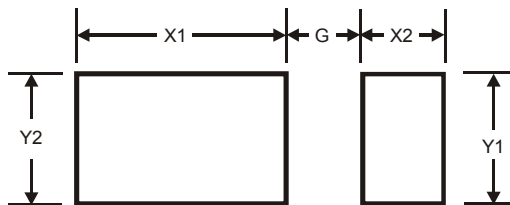
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



POWERDI [®] 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.40	0.50	0.45
L1	1.25	1.40	1.35
L2	1.025	1.125	1.10
L3	0.125	0.275	0.20
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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